

Transaction Information

Tool ID	CMPO-512
Tool Status	Connected
Location	Woodlands, Singapore
Wafer Size	200 mm
Fab Section	CMP
Tool Available Date	2023-12-22

General Product Information

Vendor Supplier	EBARA CORPORATION TOKYO JAPAN
Model	EPO-222
Vintage	1999
Serial No	PTD90457EX
Asset Description	Ebara 222 Oxide CMP Polisher
Software Version	3.5.14
CIM	SECS/GEM
Process	ILD/IMD CMP Oxide

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Handler System	Robot 1 & Robot 2	2	OK
Factory Interface	SMIF	2	OK
Others			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
NONE	0	

Missing/Faulty Parts / Accesories List

Description	Quantity
NONE	0

Tool Pictures

General

CMPO-512 Physical Tool View



Hardware Fab

200mm Ebara222 Oxide Eqpt
Config(CMPO-512)**Ebara222 Oxide CMP Equipment Configuration**

System	CMPO-512
Production	FMFG
Software	
VME (Tool Version)	03.13.31
Touch Panel Version	3.5.14
Endpoint	NA
Hardware	
Polishing Unit	RPC
a) RPC Top Ring Assembly (T1/T2)	Yes/Yes
b) Atomizer Function	Yes
c) Spray bar	# Nozzles
Pusher Unit	Enhanced Nozzles
Dressing Unit	Lightweigh
Turn-Over Unit (Dry & Wet)	In-use
Roll Cleaning Unit	New Stage Clamps
Pencil Cleaning Unit	222 Sponge
Slurry Supply Unit	LineA-CLC
Load/Unload Unit	Inx2200
Robot Unit Rorze	Yes
a) Robot1	Yes
b) Robot2	Yes
Upgrade / CIP Retrofit Items	
DTR Pressure Alarm (Lower Limit/Upper Limit)	Yes
Atomizer Spray Bar	Yes
Roll Unit Stage Clamps	Yes
Roll Unit Stage Belts	Yes
DTR DIW Flow Rate meter	Yes

Ebara222 Oxide



Hardware Sub-fab	Chemicals used on CMPO-512
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Polisher: Oxide Slurry pH ~ 11, supply to POU at Turn Table.	
Cleaner: 2% Ammonia (NH ₄ OH), supply to Roll-Roll Station.	

Manufacture Serial

CMPO-512 Tool SN

EBARA CMP

MODEL

EPO 2228

VOLTAGE

208 V

DATE

1999. 2

PHASE/WIRE

3 PHASE 4 WIRES

SER. No.

PTD90457EX

FREQUENCY

50 Hz

ELECTRIC CURRENT

125 A



EBARA CORPORATION

TOKYO JAPAN

Please read the instruction manual.

Missing Parts	All parts are intact
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All parts are intact.

Additional Configuration Files

Ebara222 Oxide CMP Equipment Configuration

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